

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	"6429506" and thermoplastic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 16:01
L2	1	"6555417".PN.	USPAT; USOCR	OR	ON	2005/06/25 15:58
L3	1	"6410360".PN.	USPAT; USOCR	OR	ON	2005/06/25 15:59
L4	1	"6109113".PN.	USPAT; USOCR	OR	ON	2005/06/25 15:59
L5	1	"6106735".PN.	USPAT; USOCR	OR	ON	2005/06/25 15:59
L6	1	"5831162".PN.	USPAT; USOCR	OR	ON	2005/06/25 15:59
L7	138	mold adj caps and thermoplastic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 16:06
L8	23	mold adj caps same thermoplastic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 16:00
L9	11	"6429506"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 16:01
L10	1	"4791075".PN.	USPAT; USOCR	OR	ON	2005/06/25 16:05
L11	1	"4656442".PN.	USPAT; USOCR	OR	ON	2005/06/25 16:05
L12	14	mold adj caps and thermoplastic and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 16:09
L13	527	(438/112).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 16:09

Search Notes

L14	911	(438/125).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 16:11
L17	9	thermoplastic and mold adj caps and wafer and chips	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 16:41
L18	12	(("5,521,123") or ("6,429,506") or ("5,789,307") or ("6,255,741") or ("4,483,194") or ("5,095,752")). PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/25 17:45
L19	21	"5521123"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 18:18
L20	26	mold same cap same thermoplastic and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 18:21
L21	633	mold same thermoplastic and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 18:21
L22	276	mold same thermoplastic and wafer and chip and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 18:21
L23	45	silicon same mold same thermoplastic and wafer and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 18:21
S1	842	mold and cap and thermoplastic and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/25 15:54
S2	56	mold same cap same thermoplastic and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 18:02

S3	36	mold same cap same thermoplastic and chip and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 17:51
S4	2992	(438/106).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/18 17:51
S5	405	(438/110).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/18 17:52
S6	890	(438/113).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/18 17:52
S7	905	(438/125).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/18 17:52
S8	0	S7 and mold and cpas	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 17:52
S9	15	S7 and mold and cap	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 17:52
S10	2	("6429506").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/18 19:27
S11	2	("5798557").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/18 19:07
S12	2	("6350113").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/18 18:40

S13	2	("6390439").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/18 18:40
S14	38	"5798557"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 19:07
S15	11	"6429506"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 19:16
S16	1	"6429506".PN.	USPAT; USOCR	OR	ON	2005/06/18 19:16
S17	11	"6429506"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 19:30
S18	21	"5521123"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 19:53
S19	1961	Silverbrook-Kia.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 19:53
S20	186	Silverbrook-Kia.in. and semiconductor and mold	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 19:56
S21	56	Silverbrook-Kia.in. and semiconductor and mold and thermoplastic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 20:00
S22	11	"6374004"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/18 20:00